

Title of Change:	Qualification of the Manufacturing of QFN20 4X4 Assembly Devices at UTAC Thai Limited.			
Proposed first ship date:	26 December 2018 or earlier upon customer approval			
Contact information:	Contact your local ON Semiconductor Sales Office or <peter.vo@onsemi.com></peter.vo@onsemi.com>			
Samples:	Contact your local ON Semiconductor Sales Office or < <u>PCN.samples@onsemi.com</u> > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.			
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <phine.guevarra@onsemi.com></phine.guevarra@onsemi.com>			
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < <u>PCN.Support@onsemi.com></u>			
Change Part Identification:	Affected parts are marked with the manufacturing site code, "G", for UTAC Thai Limited.			
Change Category:	Wafer Fab Change Assembly Change	Test Change Other		
Change Sub-Category(s): Manufacturing Site Additi Manufacturing Site Transf Manufacturing Process Ch	er Product specific change	 Datasheet/Product Doc change Shipping/Packaging/Marking Other: 		
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: UTAC		
Description and Purpose:				
This final product change notification is to inform the qualification of assembly manufacturing of the affected parts of package type QFN20 4x4 at UTAC Thai Limited. Upon execution, products can be manufactured at either ON Semiconductor Seremban in Malaysia or UTAC Thai Limited in Thailand, Bangkok. This change is to allow better management of the supply chain to meet customers' demands. The BOM qualified at UTAC are standard material. There is no product marking change as a result of this change.				

	Before Change Description	After Change Description	
Assembly Site	ON Semiconductor Seremban	UTAC Thailand	ON Semiconductor Seremban
Ероху	AB 8006NS	8600	AB 8006NS
Mold Compound	SU EMEG760	G700LTD	SU EMEG760



Reliability Data Summary:

QV DEVICE NAME: NCN5150MNTWG RMS: O46924, O49224 PACKAGE: QFN20 4X4

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/135
тс	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/480
SD	JSTD002	Ta = 245C, 10 sec		0/15

Electrical Characteristic Summary:

Electrical characteristics are not impacted by this change.

List of Affected Parts:

Part Number	Qualification Vehicle	
NCN5150MNTWG	NCN5150MNTWG	
NCN5151MNTWG	NCN5150MNTWG	